

# **C3D08065I**Silicon Carbide Schottky Diode

Z-REC<sup>™</sup> RECTIFIER

 $\mathbf{V}_{RRM}$  = 650 V  $\mathbf{I}_{F}(\mathbf{T}_{c}=\mathbf{125}^{\circ}\mathbf{C}) = 8 \text{ A}$  $\mathbf{Q}_{c}$  = 21 nC

#### **Features**

- 650-Volt Schottky Rectifier
- Ceramic Package provides 2.5kV isolation
- Zero Reverse Recovery Current
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- Positive Temperature Coefficient on V<sub>F</sub>

## **Benefits**

- Electrically Isolated Package
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway

# **Applications**

- HVAC
- Switch Mode Power Supplies

## **Package**









Part Number	Package	Marking
C3D08065I	Isolated TO-220-2	C3D08065I

# **Maximum Ratings**

Symbol	Parameter	Value	Unit	Test Conditions	Note
V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	650	V		
$V_{RSM}$	Surge Peak Reverse Voltage	650	V		
V <sub>DC</sub>	DC Blocking Voltage	650	V		
$I_{_{\rm F}}$	Continuous Forward Current	15.2 8 7	А	T <sub>c</sub> =25°C T <sub>c</sub> =125°C T <sub>c</sub> =135°C	See Fig 3
$\mathbf{I}_{FRM}$	Repetitive Peak Forward Surge Current	29 19	А	$T_c$ =25°C, $t_p$ =10 ms, Half Sine pulse $T_c$ =110°C, $t_p$ =10 ms, Half Sine pulse	
$\boldsymbol{I}_{\text{FSM}}$	Non-Repetitive Peak Forward Surge Current	69 55	А	$T_c$ =25 °C, $t_p$ =10 ms, Half Sine pulse $T_c$ =110 °C, $t_p$ =10 ms, Half Sine pulse	
$P_{tot}$	Power Dissipation	48 20	W	T <sub>c</sub> =25°C T <sub>c</sub> =110°C	
T,	Operating Junction Range	-55 to +175	°C		
$T_{stg},T_{c}$	Storage Temperature and Case Temperature	-55 to +150	°C		
	TO-220 Mounting Torque	1 8.8	Nm lbf-in	M3 Screw 6-32 Screw	



## **Electrical Characteristics**

Symbol	Parameter	Тур.	Max.	Unit	Test Conditions	Note
V <sub>F</sub>	Forward Voltage	1.5 2.0	1.8 2.4	V	$I_F = 8 \text{ A } T_J = 25^{\circ}\text{C}$ $I_F = 8 \text{ A } T_J = 175^{\circ}\text{C}$	
I <sub>R</sub>	Reverse Current	12 24	60 220	μΑ	$V_R = 650 \text{ V } T_J = 25^{\circ}\text{C}$ $V_R = 650 \text{ V } T_J = 175^{\circ}\text{C}$	
Q <sub>c</sub>	Total Capacitive Charge	21		nC	$V_R = 650 \text{ V, } I_F = 8A$ $di/dt = 500 \text{ A/}\mu\text{s}$ $T_J = 25^{\circ}\text{C}$	
С	Total Capacitance	441 39 33		pF	$V_R = 0 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$ $V_R = 200 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$ $V_R = 400 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$	

#### Note:

## **Thermal Characteristics**

Symbol	Parameter	Тур.	Unit
$R_{\theta JC}$	Package Thermal Resistance from Junction to Case	3.1	°C/W

# **Typical Performance**

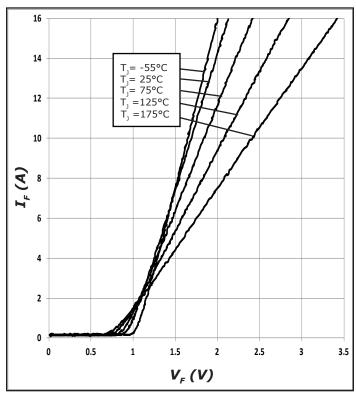


Figure 1. Forward Characteristics

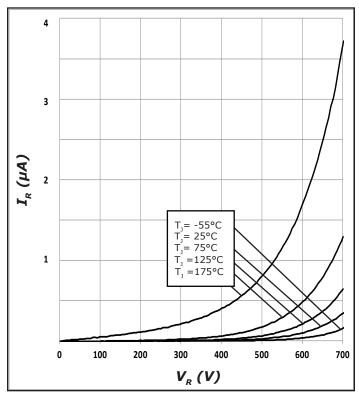
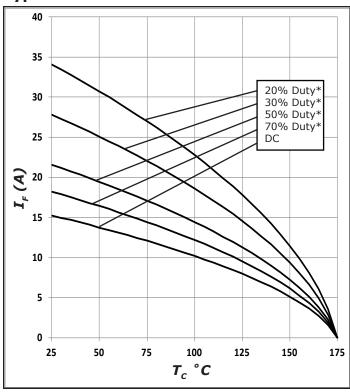


Figure 2. Reverse Characteristics

<sup>1.</sup> This is a majority carrier diode, so there is no reverse recovery charge.



## **Typical Performance**



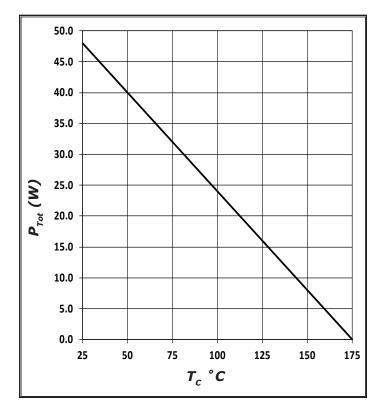


Figure 3. Current Derating

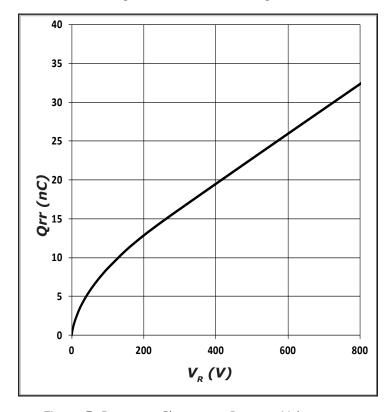


Figure 5. Recovery Charge vs. Reverse Voltage

Figure 4. Power Derating

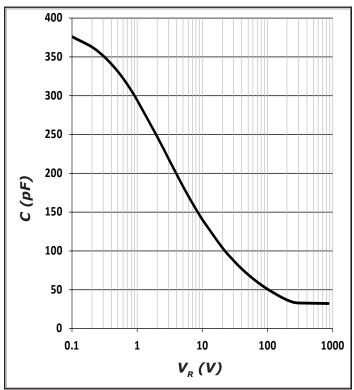


Figure 6. Capacitance vs. Reverse Voltage



## **Typical Performance**

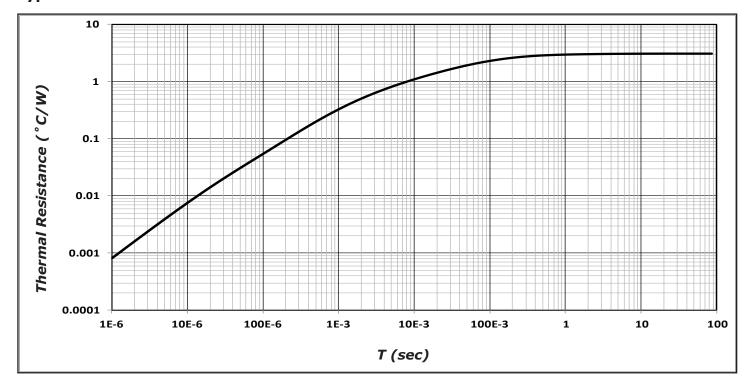


Figure 7. Transient Thermal Impedance

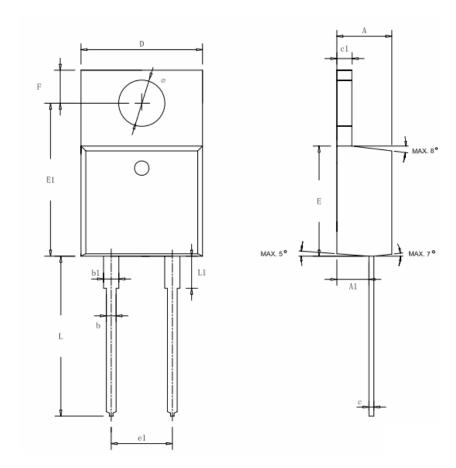
## **Diode Model**

$$Vf_T = V_T + If^*R_T$$
 
$$V_T = 0.98 + (T_J^* - 1.6^*10^{-3})$$
 
$$R_T = 0.04 + (T_J^* 0.522^*10^{-3})$$

Note:  $T_i$  = Diode Junction Temperature In Degrees Celsius



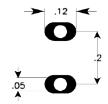
# **Package Dimensions**



	Dimensions i	n Millimeters	limeters Dimensions in Inches		
Symbol	Min	Max	Min	Max	
Α	4.420	4.720	1.174	0.186	
A1	2.520	2.820	0.099	0.111	
b	0.710	0.910	0.028	0.036	
<b>b1</b>	1.170	1.370	0.046	0.054	
С	0.360	0.460	0.014	0.018	
<b>c1</b>	1.170	1.370	0.046	0.054	
D	9.950	10.250	0.392	0.404	
E	8.930	9.290	0.352	0.366	
E1	12.550	12.850	0.494	0.506	
e1	4.980	5.180	0.196	0.204	
F	2.590	2.890	0.102	0.114	
L	13.080	13.480	0.515	0.531	
L1	2.470	2.870	0.097	0.113	
ф	3.790	3.890	0.149	0.153	



## **Recommended Solder Pad Layout**



Measurements shown in inches TO-220-2

Part Number	Package	Marking
C3D08065I	Isolated TO-220-2	C3D08065I

Note: Recommended soldering profiles can be found in the applications note here: http://www.cree.com/power\_app\_notes/soldering



#### **Notes**

#### RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Cree representative or from the Product Documentation sections of www.cree.com.

#### REACh Compliance

REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Cree representative to insure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

This product has not been designed or tested for use in, and is not intended for use in, applications implanted into
the human body nor in applications in which failure of the product could lead to death, personal injury or property
damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines,
cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control
systems, air traffic control systems, or weapons systems.

Copyright © 2013 Cree, Inc. All rights reserved. The information in this document is subject to change without notice. Cree, the Cree logo, and Zero Recovery are registered trademarks of Cree, Inc.